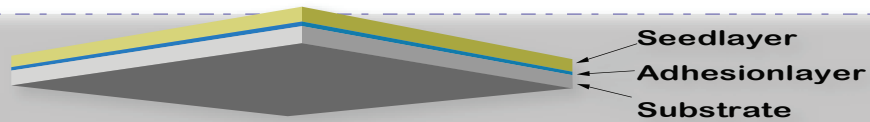


UV-LIGA: Schematic process

Step 1:
Deposition of
Adhesion / Seedlayer

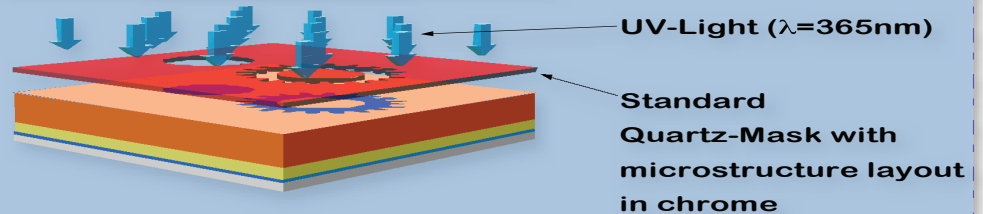


Lithographie

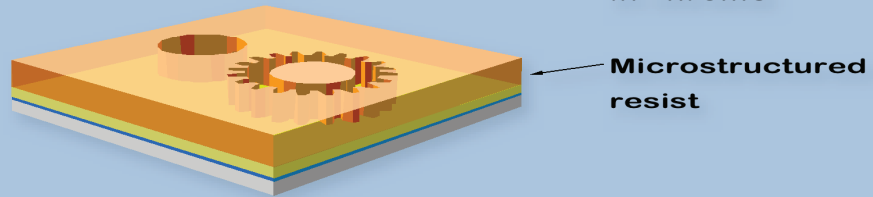
Step 2:
Resist coating



Step 3:
UV-Exposure

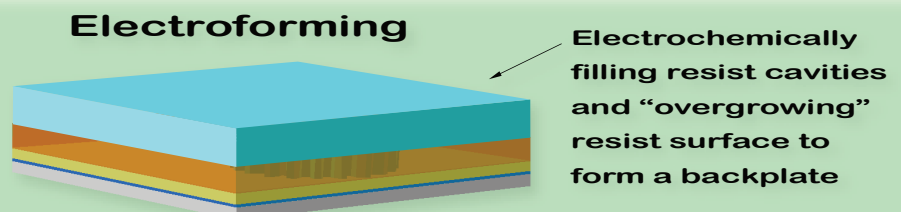


Step 4:
Spray development
of exposed resist

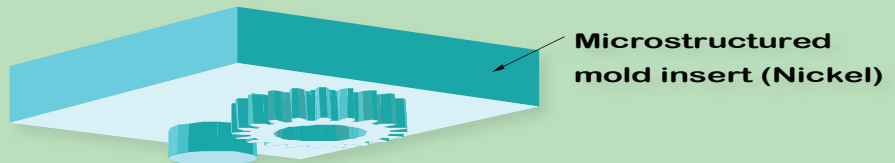


Galvanik

Step 5:
Nickel electroforming

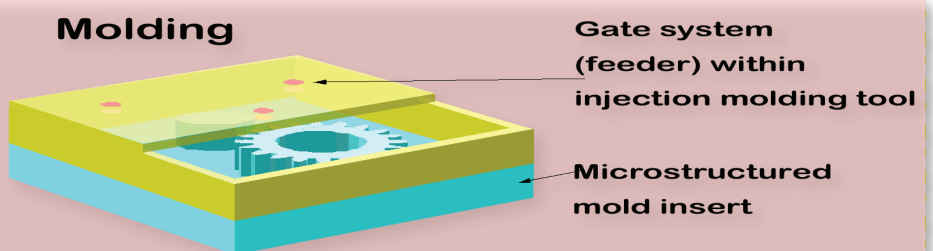


Step 6:
Removal of resist and
substrate incl.
shaping tool dimensions



Abformung

Step 7:
"Filling" the
microstructured
tool cavity with polymer



Step 8:
Ejection and
singulation

